- AC Types Feature 1.5-V to 5.5-V Operation and Balanced Noise Immunity at 30% of the Supply Voltage
- Speed of Bipolar F, AS, and S, With Significantly Reduced Power Consumption
- Balanced Propagation Delays
- ±24-mA Output Drive Current
 Fanout to 15 F Devices
- SCR-Latchup-Resistant CMOS Process and Circuit Design
- Exceeds 2-kV ESD Protection Per MIL-STD-883, Method 3015

Ś	SCHS336 – MARCH 2003										
M PACKAGE (TOP VIEW)											
$ \begin{array}{c c} \hline A/B & 1 & 16 \\ 1A & 2 & 15 \\ 1B & 3 & 14 \\ 1Y & 4 & 13 \\ 2A & 5 & 12 \\ 2B & 6 & 11 \\ 2Y & 7 & 10 \\ 3B \\ GND & 8 & 9 \\ 3Y \end{array} $	с										

description/ordering information

This quadruple 2-line to 1-line data selector/multiplexer is designed for 1.5-V to 5.5-V V_{CC} operation.

The CD74AC158 features a common strobe (\overline{G}) input. When the strobe is high, all outputs are high. When the strobe is low, a 4-bit word is selected from one of two sources and is routed to the four outputs. This device provides inverted data.

ORDERING INFORMATION

TA	PACKA	GE†	ORDERABLE PART NUMBER	TOP-SIDE MARKING
–55°C to 125°C	SOIC – M	Tube	CD74AC158M	AC158M

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

<u> </u>	(each data selector/multiplexer)											
	INPU	OUTPUT										
G	A/B	Α	В	Y								
Н	Х	Х	Х	Н								
L	L	L	х	н								
L	L	Н	Х	L								
L	Н	Х	L	Н								
L	н	Х	н	L								

FUNCTION TABLE (each data selector/multiplexer)



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

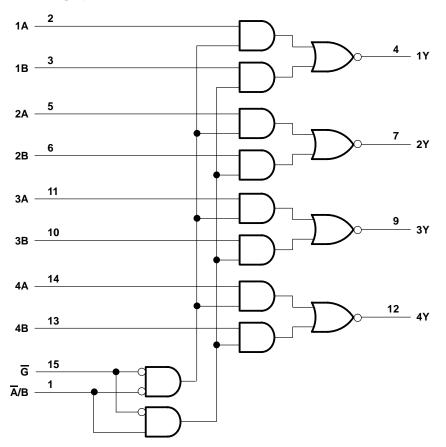
PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



Copyright © 2003, Texas Instruments Incorporated

SCHS336 - MARCH 2003

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V _{CC}	–0.5 V to 6 V
Input clamp current, I_{IK} ($V_I < 0$ V or $V_I > V_{CC}$) (see Note 1)	±20 mA
Output clamp current, I _{OK} (V _O < 0 V or V _O > V _{CC}) (see Note 1)	±50 mA
Continuous output current, $I_O (V_O > 0 V \text{ or } V_O < V_{CC})$	±50 mA
Continuous current through V _{CC} or GND	
Package thermal impedance, θ_{JA} (see Note 2)	73°C/W
Storage temperature range, T _{stg}	. –65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.



SCHS336 - MARCH 2003

recommended operating conditions (see Note 3)

			T _A = 25°C		–55°C to 125°C		–40° 85°		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
VCC	Supply voltage		1.5	5.5	1.5	5.5	1.5	5.5	V
		V _{CC} = 1.5 V	1.2		1.2		1.2		
VIH	High-level input voltage	$V_{CC} = 3 V$	2.1		2.1		2.1		V
		$V_{CC} = 5.5 V$	3.85		3.85		3.85		
		V _{CC} = 1.5 V		0.3		0.3		0.3	
VIL	Low-level input voltage	$V_{CC} = 3 V$		0.9		0.9		0.9	V
		V _{CC} = 5.5 V		1.65		1.65		1.65	
VI	Input voltage		0	VCC	0	VCC	0	VCC	V
VO	Output voltage		0	VCC	0	VCC	0	VCC	V
ЮН	High-level output current	V _{CC} = 4.5 V to 5.5 V		-24		-24		-24	mA
IOL	Low-level output current	V_{CC} = 4.5 V to 5.5 V		24		24		24	mA
A+/A.v	Input transition rise or fall rate	V_{CC} = 1.5 V to 3 V		50		50		50	no/\/
Δt/Δv	Input transition rise or fall rate	V _{CC} = 3.6 V to 5.5 V		20		20		20	ns/V

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CON	IDITIONS	Vcc	T _A = 25°C		°C to 25°C	–40° 85°		UNIT
				MIN MA	X MIN	MAX	MIN	MAX	
			1.5 V	1.4	1.4		1.4		
		I _{OH} = -50 μA	3 V	2.9	2.9		2.9		
			4.5 V	4.4	4.4		4.4		
∨он	$V_I = V_{IH} \text{ or } V_{IL}$	I _{OH} =4 mA	3 V	2.58	2.4		2.48		V
		I _{OH} = -24 mA	4.5 V	3.94	3.7		3.8		
		I _{OH} = -50 mA [†]	5.5 V		3.85				
		I _{OH} = -75 mA†	5.5 V				3.85		
			1.5 V	0	.1	0.1		0.1	
		I _{OL} = 50 μA	3 V	0	.1	0.1		0.1	
			4.5 V	0	.1	0.1		0.1	
VOL	$V_I = V_{IH} \text{ or } V_{IL}$	I _{OL} = 12 mA	3 V	0.3	36	0.5		0.44	V
		I _{OL} = 24 mA	4.5 V	0.3	36	0.5		0.44	
		$I_{OL} = 50 \text{ mA}^{\dagger}$	5.5 V			1.65			
		I _{OL} = 75 mA [†]	5.5 V					1.65	
lj	$V_I = V_{CC}$ or GND		5.5 V	±0	.1	±1		±1	μA
ICC	$V_I = V_{CC}$ or GND,	IO = 0	5.5 V		8	160		80	μA
Ci					0	10		10	pF

[†] Test one output at a time, not exceeding 1-second duration. Measurement is made by forcing indicated current and measuring voltage to minimize power dissipation. Test verifies a minimum 50-Ω transmission-line drive capability at 85°C and 75-Ω transmission-line drive capability at 125°C.



SCHS336 - MARCH 2003

switching characteristics over recommended operating free-air temperature range, $V_{CC} = 1.5 \text{ V}$, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	–55°C 125°		–40°(85°	UNIT		
		(001F01)	MIN	MAX	MIN	MAX		
^t PLH	A or B							
^t PHL	AUB	Any Y		100		91	ns	
^t PLH	Ā/B	161			147	20		
^t PHL	А/В	Any Y		161		147	ns	
^t PLH	IJ			149		135		
^t PHL	9	Any Y		149		135	ns	

switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	–55° 125		–40° 85°	UNIT	
			MIN	MAX	MIN	MAX	
^t PLH	A or B		2.8	11.2	3	12.8	ns
^t PHL	AOIB	Any Y	2.8	11.2	3	12.8	115
^t PLH	Ā/B	Any Y	4.5	18.1	4.9	16.5	ns
^t PHL	A/B		4.5	18.1	4.9	16.5	115
^t PLH	G	Any Y	4.2	16.7	4.5	15.2	ns
^t PHL	0	Ally I	4.2	16.7	4.5	15.2	115

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V, C_L = 50 pF (unless otherwise noted) (see Figure 1)

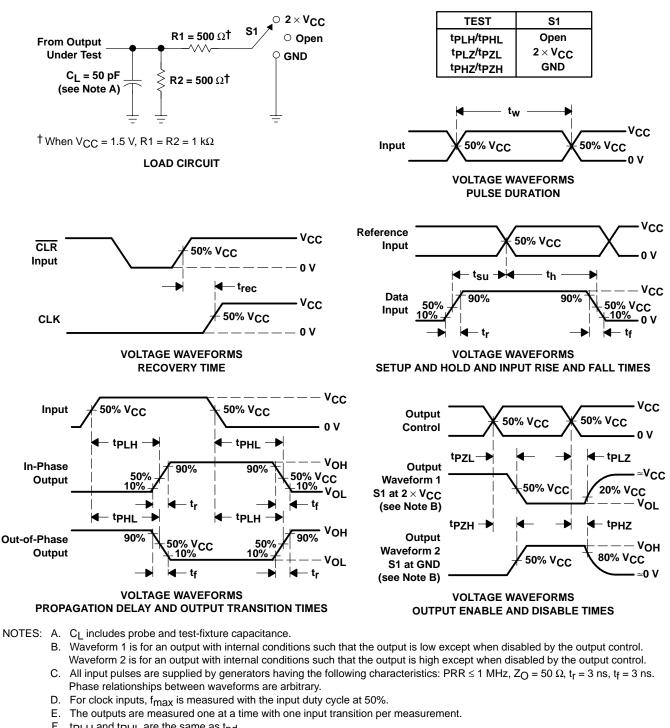
PARAMETER	FROM (INPUT)	TO (OUTPUT)	–55°(125		–40°(85°	UNIT	
		(001F01)	MIN	MAX	MIN	MAX	
^t PLH	A or B		2	8	2.2	7.3	20
^t PHL	AOIB	Any Y	2	8	2.2	7.3	ns
^t PLH	Ā/B		3.2	12.9	3.5	11.7	20
^t PHL	A/B	Any Y	3.2	12.9	3.5	11.7	ns
^t PLH	G	Any Y	3	11.9	3.2	10.8	ns
^t PHL	0		3	11.9	3.2	10.8	115

operating characteristics, V_{CC} = 5 V, T_A = 25° C

	PARAMETER					
C _{pd}	Power dissipation capacitance	149	pF			



SCHS336 - MARCH 2003



PARAMETER MEASUREMENT INFORMATION

- F. tpLH and tpHL are the same as tpd.
- G. t_{PZL} and t_{PZH} are the same as t_{en} .
- H. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
- I. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms





6-Feb-2020

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package	Pins	Package	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
CD74AC158M	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-55 to 125	AC158M	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer:The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



4211283-4/E 08/12

D (R-PDSO-G16) PLASTIC SMALL OUTLINE Stencil Openings (Note D) Example Board Layout (Note C) –16x0,55 -14x1,27 -14x1,27 16x1,50 5,40 5.40 Example Non Soldermask Defined Pad Example Pad Geometry (See Note C) 0,60 .55 Example 1. Solder Mask Opening (See Note E) -0,07 All Around

NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, or other requirements. These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale (www.ti.com/legal/termsofsale.html) or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2020, Texas Instruments Incorporated